



GE Energy

Functional Testing Specification

*Parts & Repair Operations
Louisville, KY*

**LOU-GEF-IC600xx900-A
Transmitter Cards**

Test Procedure for a Series Six I/O Transmitter card

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1. SCOPE

1.1 This is a functional testing procedure for a Series Six I/O Transmitter card.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to the local documented procedures for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires: broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors: broken or cracked

4.2.1.3 Components: visually damaged

4.2.1.4 Capacitors: bloated or leaking

4.2.1.5 Solder joints: damaged or cold

4.2.1.6 Circuit board: burned or de-laminated

4.2.1.7 Printed wire runs / Traces: burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Series Six CPU-3 <u>LOCAL</u> Rack-1

6. SETUP

6.1 Ensure that the berg jumpers of the card are set to the factory default positions.

7. TEST PROCESS

7.1 Ensure that the power to the CPU-3 LOCAL rack 1 is off.

7.2 Disconnect the I/O cable from the shop card.

7.3 Extract the shop card from slot 4 of the rack.

7.4 The addressing is set via the dipswitches in the back plane of the rack. Ensure that the dipswitches are set in accordance to the following chart.

1	2	3	4	5	6	7
Opened	Opened	Closed	Closed	Opened	Closed	Closed

Chart 1

7.5 Insert the card to be tested into slot 4 of the rack.

7.6 Connect the I/O cable to the card.

7.7 Turn on the power to the rack.

7.8 Give the system approximately 30 to 60 seconds to complete communication from rack to rack.

7.9 Ensure that the corresponding input and output cards light up in a scrolling fashion.

7.10 Allow the card to run for at least one half hour.

7.11 Turn off power to the rack.

8. NOTES

8.1 None at this time

9. ATTACHMENTS

9.1 None at this time